

74LVC244A-Q100; 74LVCH244A-Q100

Quad buffer/line driver; 3-state

Rev. 2 — 13 August 2013

Product data sheet

1. General description

The 74LVC244A-Q100; 74LVCH244A-Q100 is an octal non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs $\overline{1OE}$ and $\overline{2OE}$. A HIGH on \overline{nOE} causes the outputs to assume a high-impedance OFF-state. Schmitt-trigger action at all inputs makes the circuit highly tolerant for slower input rise and fall times.

Inputs can be driven from either 3.3 V or 5.0 V devices. In 3-state operation, outputs can handle 5 V. These features allow the use of these devices as translators in a mixed 3.3 V and 5 V environment.

The 74LVCH244A-Q100 bus hold on data inputs eliminates the need for external pull-up resistors to hold unused inputs.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low-power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- High-impedance when $V_{CC} = 0\text{ V}$
- Bus hold on all data inputs (74LVCH244A-Q100 only)
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\text{ }\Omega$)
- Multiple package options



3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC244AD-Q100	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74LVCH244AD-Q100				
74LVC244ADB-Q100	-40 °C to +125 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74LVCH244ADB-Q100				
74LVC244APW-Q100	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74LVCH244APW-Q100				
74LVC244ABQ-Q100	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
74LVCH244ABQ-Q100				

4. Functional diagram

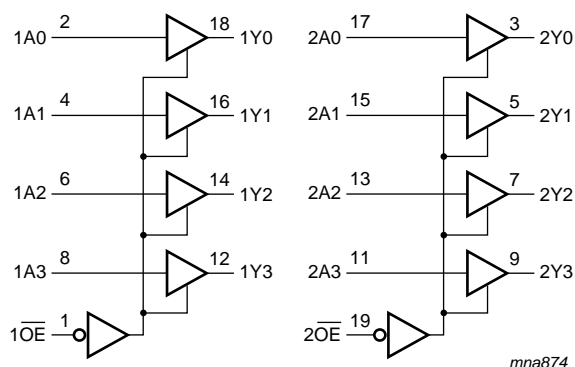


Fig 1. Logic symbol

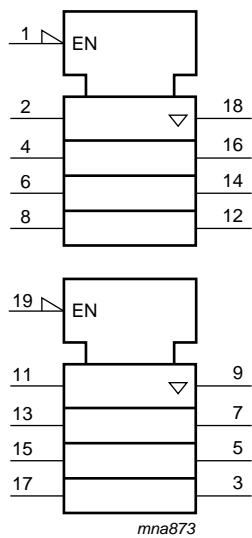


Fig 2. IEC logic diagram

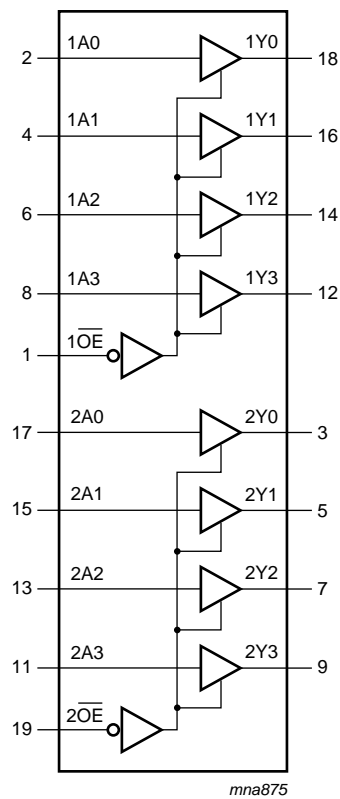
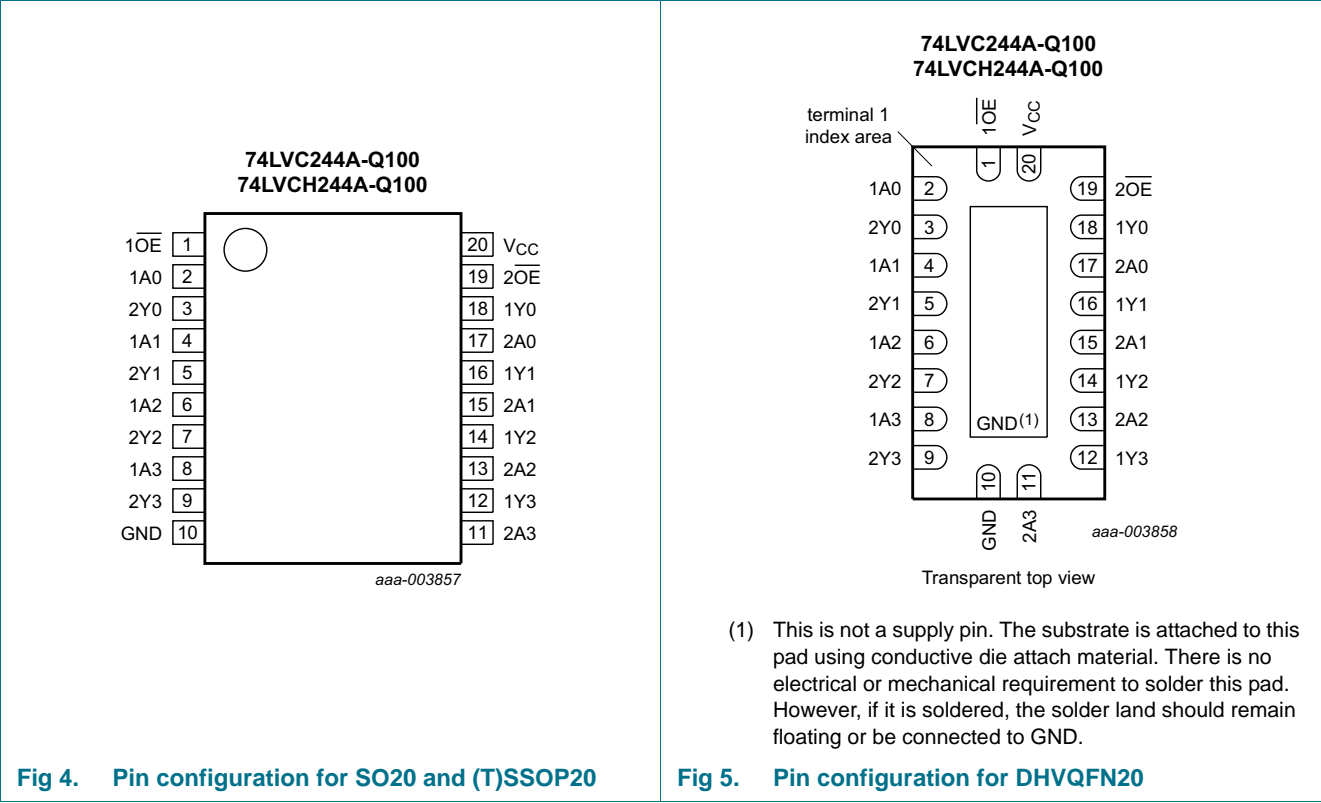


Fig 3. Functional diagram

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE	1, 19	output enable input (active low)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	data output
GND	10	ground (0 V)
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3	18, 16, 14, 12	data output
VCC	20	supply voltage

6. Functional description

Table 3. Function table [1]

Control	Input	Output
$\overline{\text{nOE}}$	nAn	nYn
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		[1] -0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
V_O	output voltage	output HIGH or LOW	[2] -0.5	$V_{CC} + 0.5$	V
		output 3-state	[2] -0.5	+6.5	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO20 packages: above 70 °C derate linearly with 8 mW/K.
 For (T)SSOP20 packages: above 60 °C derate linearly with 5.5 mW/K.
 For DHVQFN20 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	3.6	V
V _I	input voltage		0	-	5.5	V
V _O	output voltage	output HIGH or LOW	0	-	V _{CC}	V
		output 3-state	0	-	5.5	V
T _{amb}	ambient temperature	in free air	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 1.2 V to 2.7 V	0	-	20	ns/V
		V _{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	0.65 × V _{CC}	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = -100 μA; V _{CC} = 1.65 V to 3.6 V	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I _O = -18 mA; V _{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	2.2	-	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 μA; V _{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.55	-	0.8	V

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 3.6 V ^[2]	-	±0.1	±5	-	±20	μA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = 5.5 V or GND; V _{CC} = 3.6 V ^[2]	-	±0.1	±5	-	±20	μA
I _{OFF}	power-off leakage current	V _I or V _O = 5.5 V; V _{CC} = 0.0 V	-	±0.1	±10	-	±20	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 3.6 V	-	0.1	10	-	40	μA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} – 0.6 V; I _O = 0 A; V _{CC} = 2.7 V to 3.6 V	-	5	500	-	5000	μA
C _I	input capacitance		-	4.0	-	-	-	pF
I _{BHL}	bus hold LOW current	V _{CC} = 1.65 V; V _I = 0.58 V ^{[3][4]}	10	-	-	10	-	μA
		V _{CC} = 2.3 V; V _I = 0.7 V	30	-	-	25	-	μA
		V _{CC} = 3.0 V; V _I = 0.8 V	75	-	-	60	-	μA
I _{BHH}	bus hold HIGH current	V _{CC} = 1.65 V; V _I = 1.07 V ^{[3][4]}	–10	-	-	–10	-	μA
		V _{CC} = 2.3 V; V _I = 1.7 V	–30	-	-	–25	-	μA
		V _{CC} = 3.0 V; V _I = 2.0 V	–75	-	-	–60	-	μA
I _{BHLO}	bus hold LOW overdrive current	V _{CC} = 1.95 V ^{[3][5]}	200	-	-	200	-	μA
		V _{CC} = 2.7 V	300	-	-	300	-	μA
		V _{CC} = 3.6 V	500	-	-	500	-	μA
I _{BHHO}	bus hold HIGH overdrive current	V _{CC} = 1.95 V ^{[3][5]}	–200	-	-	–200	-	μA
		V _{CC} = 2.7 V	–300	-	-	–300	-	μA
		V _{CC} = 3.6 V	–500	-	-	–500	-	μA

[1] All typical values are measured at $V_{CC} = 3.3 \text{ V}$ (unless stated otherwise) and $T_{amb} = 25 \text{ }^\circ\text{C}$.[2] The bus hold circuit is switched off when $V_I > V_{CC}$ allowing 5.5 V on the input terminal.

[3] Valid for data inputs of bus hold parts only (74LVCH244A-Q100). Note that control inputs do not have a bus hold circuit.

[4] The specified sustaining current at the data input holds the input below the specified V_I level.

[5] The specified overdrive current at the data input forces the data input to the opposite input state.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	nAn to nYn; see Figure 6 ^[2]						
		V _{CC} = 1.2 V	-	17.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	6.4	13.7	1.5	15.8	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	3.4	7.1	1.0	8.2	ns
		V _{CC} = 2.7 V	1.5	3.4	6.9	1.5	9.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.5	2.9	5.9	1.5	7.5	ns
t _{en}	enable time	nOE to nYn; see Figure 7 ^[2]						
		V _{CC} = 1.2 V	-	24.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	7.0	17.3	1.5	20.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.5	3.9	9.5	1.5	11.0	ns
		V _{CC} = 2.7 V	1.5	4.1	8.6	1.5	11.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	3.2	7.6	1.0	9.5	ns
t _{dis}	disable time	nOE to nYn; see Figure 7 ^[2]						
		V _{CC} = 1.2 V	-	9.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	2.2	4.5	9.8	2.2	11.3	ns
		V _{CC} = 2.3 V to 2.7 V	0.5	3.6	5.5	0.5	6.4	ns
		V _{CC} = 2.7 V	1.5	3.3	6.8	1.5	8.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.5	3.1	5.8	1.5	7.5	ns
t _{sk(o)}	output skew time	^[3]	-	-	1.0	-	1.5	ns
C _{PD}	power dissipation capacitance	per input; V _I = GND to V _{CC} ^[4]						
		V _{CC} = 1.65 V to 1.95 V	-	6.4	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	9.6	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	12.5	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

t_{en} is the same as t_{pZL} and t_{pZH}.

t_{dis} is the same as t_{pLZ} and t_{pHZ}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz; f_o = output frequency in MHz

C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

11. AC waveforms

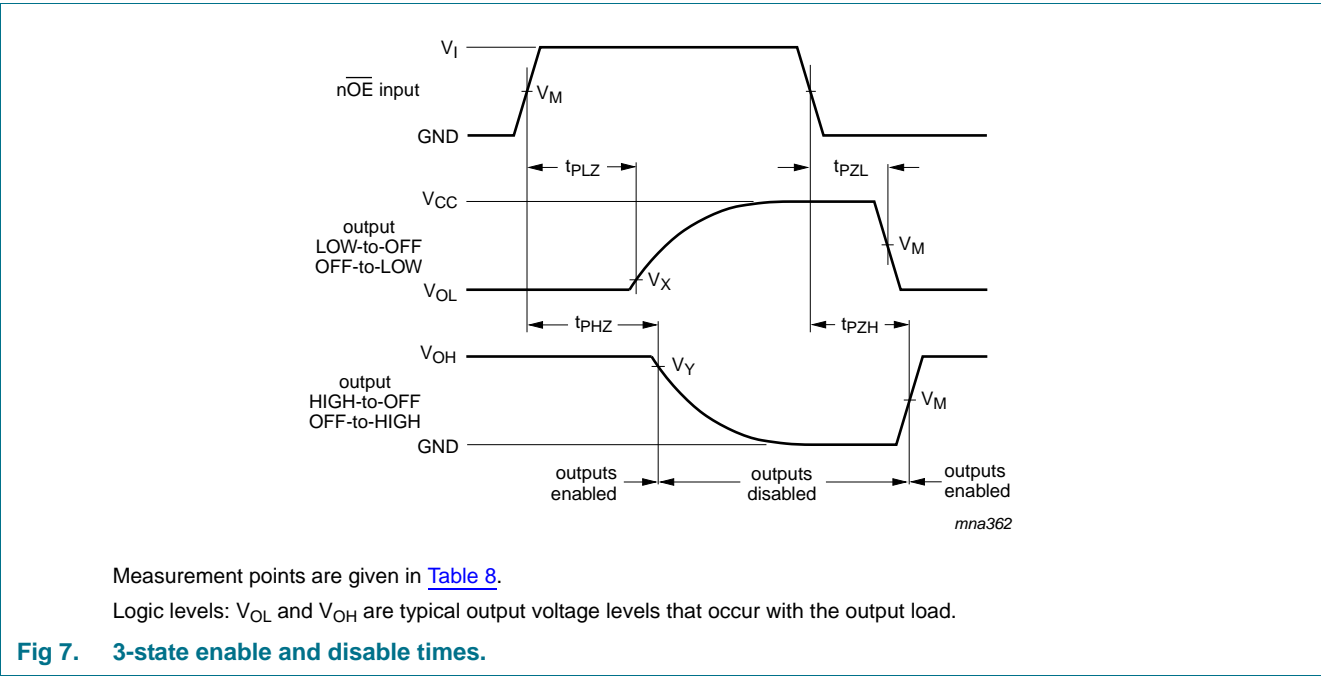
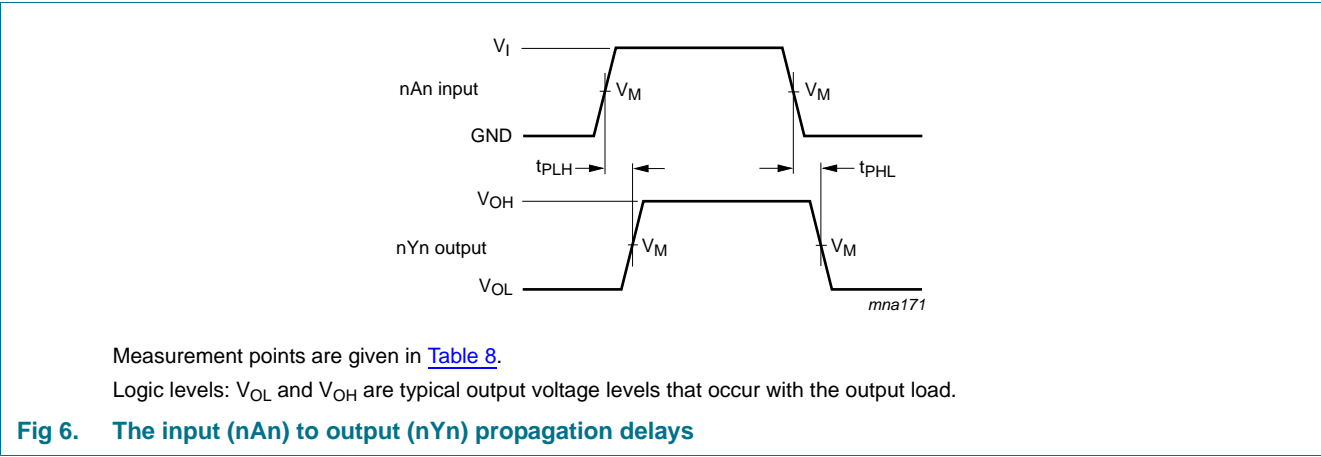
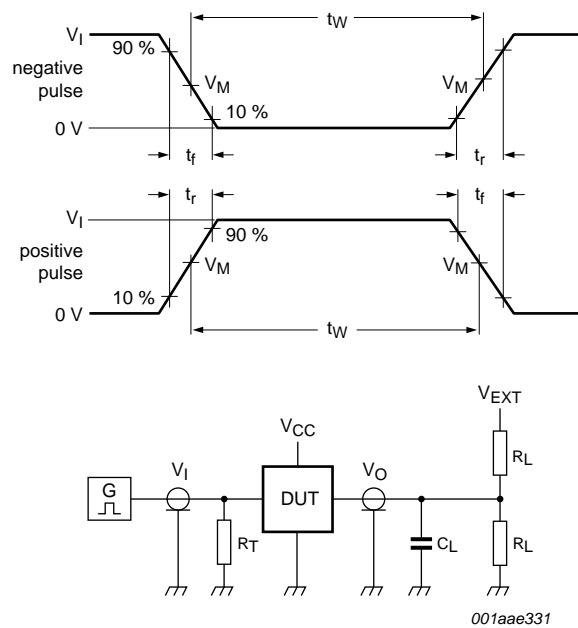


Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
1.2 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
1.65 V to 1.95 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.3 V to 2.7 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.7 V	2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 9](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

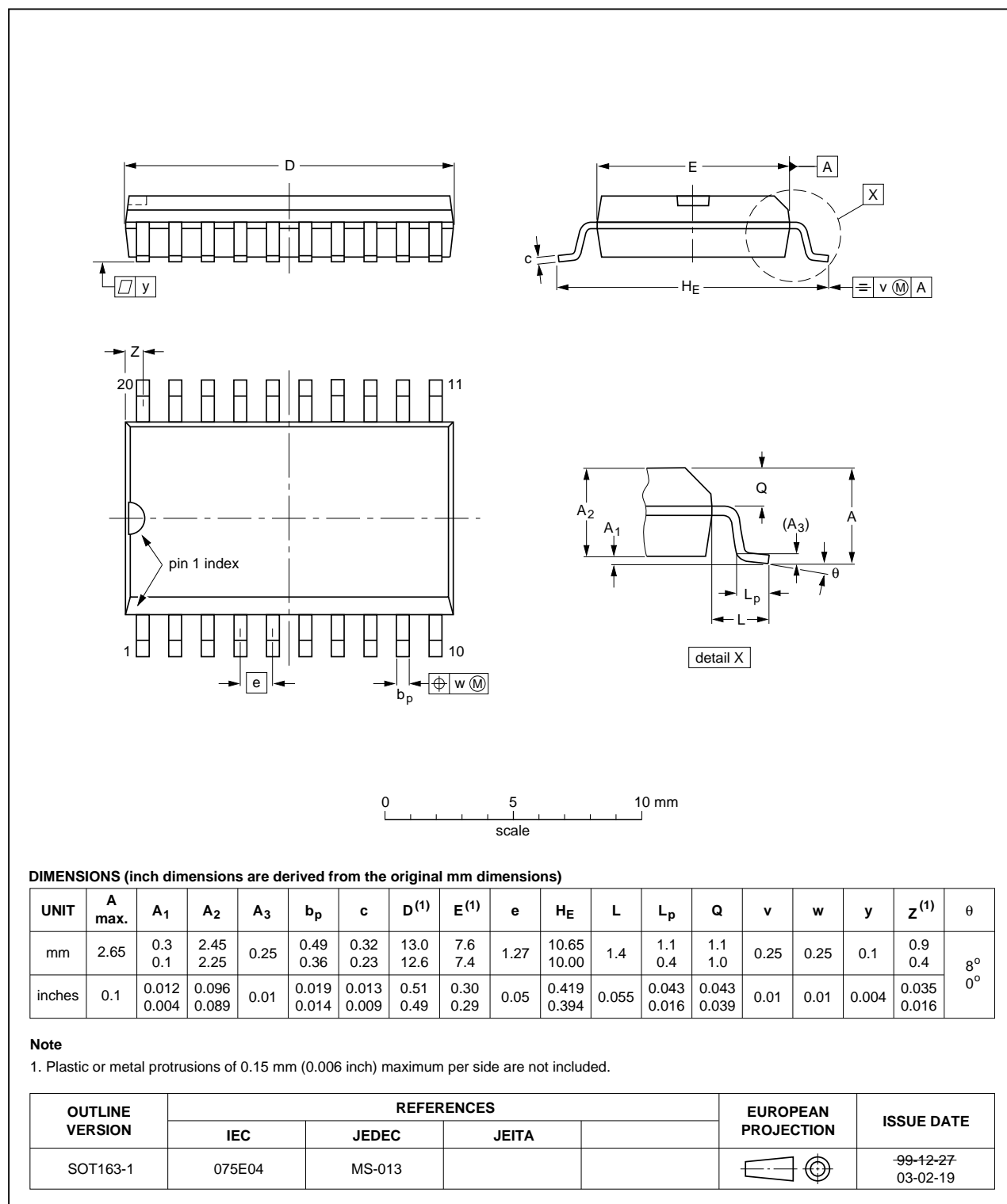


Fig 9. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

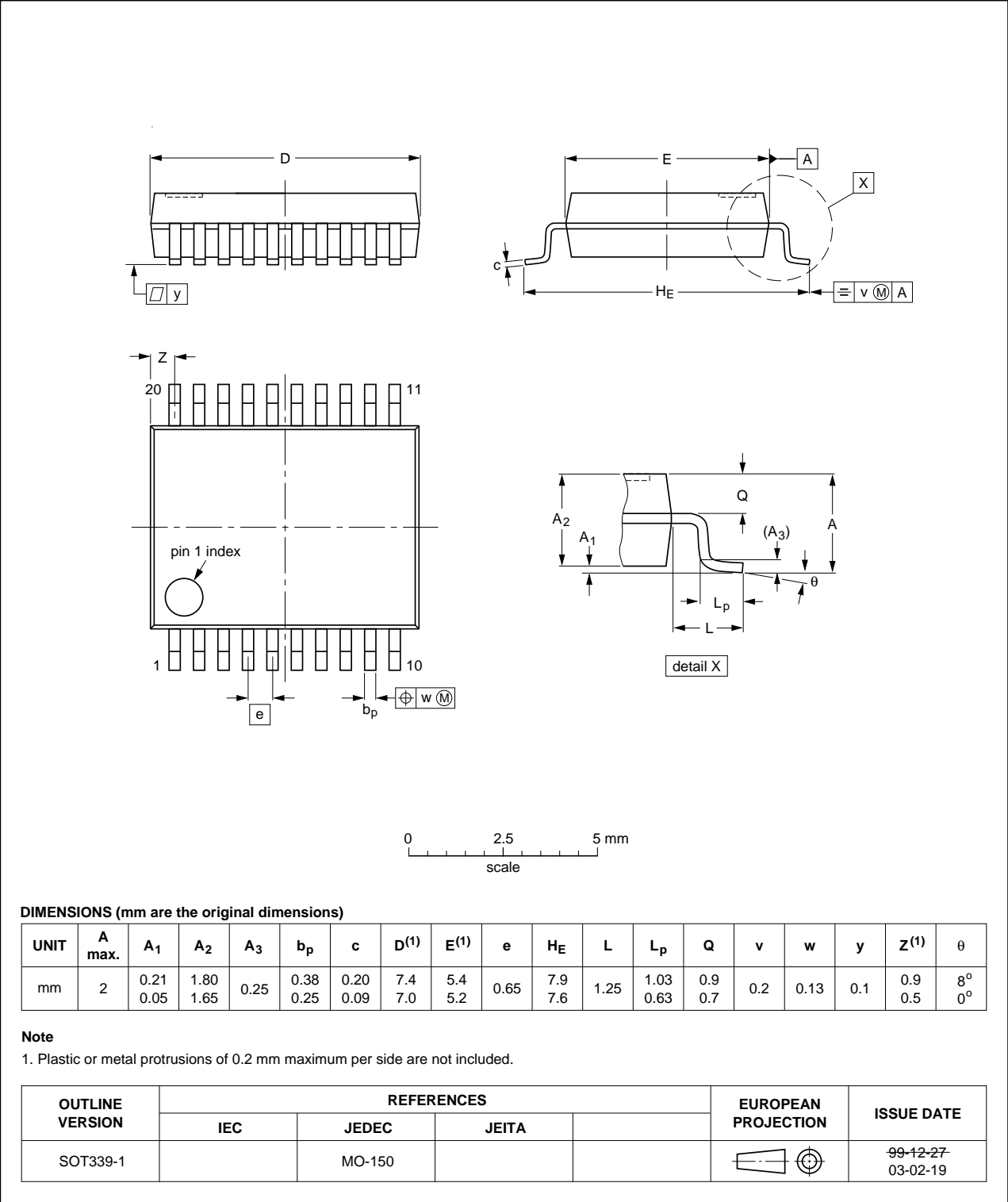


Fig 10. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

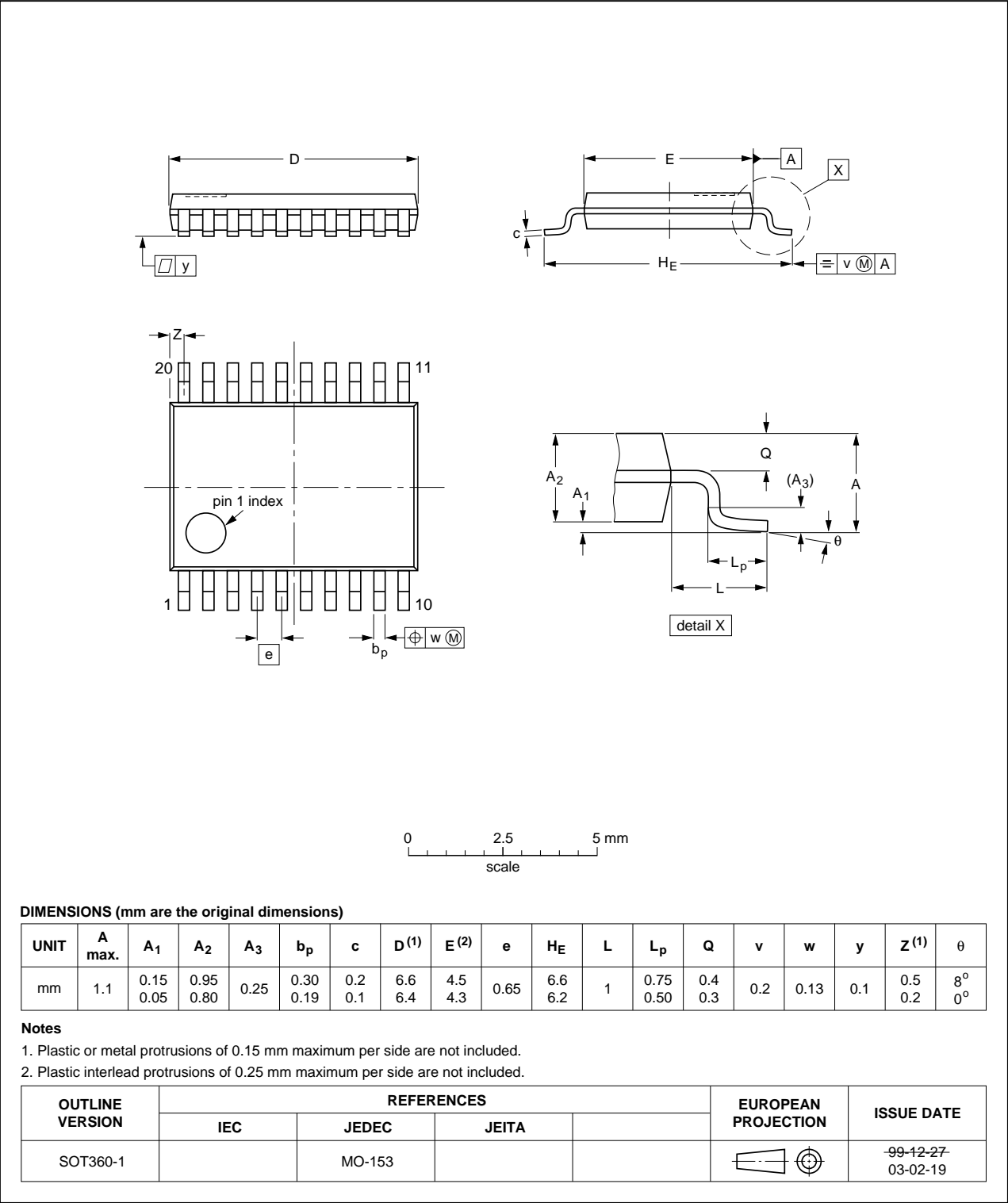


Fig 11. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

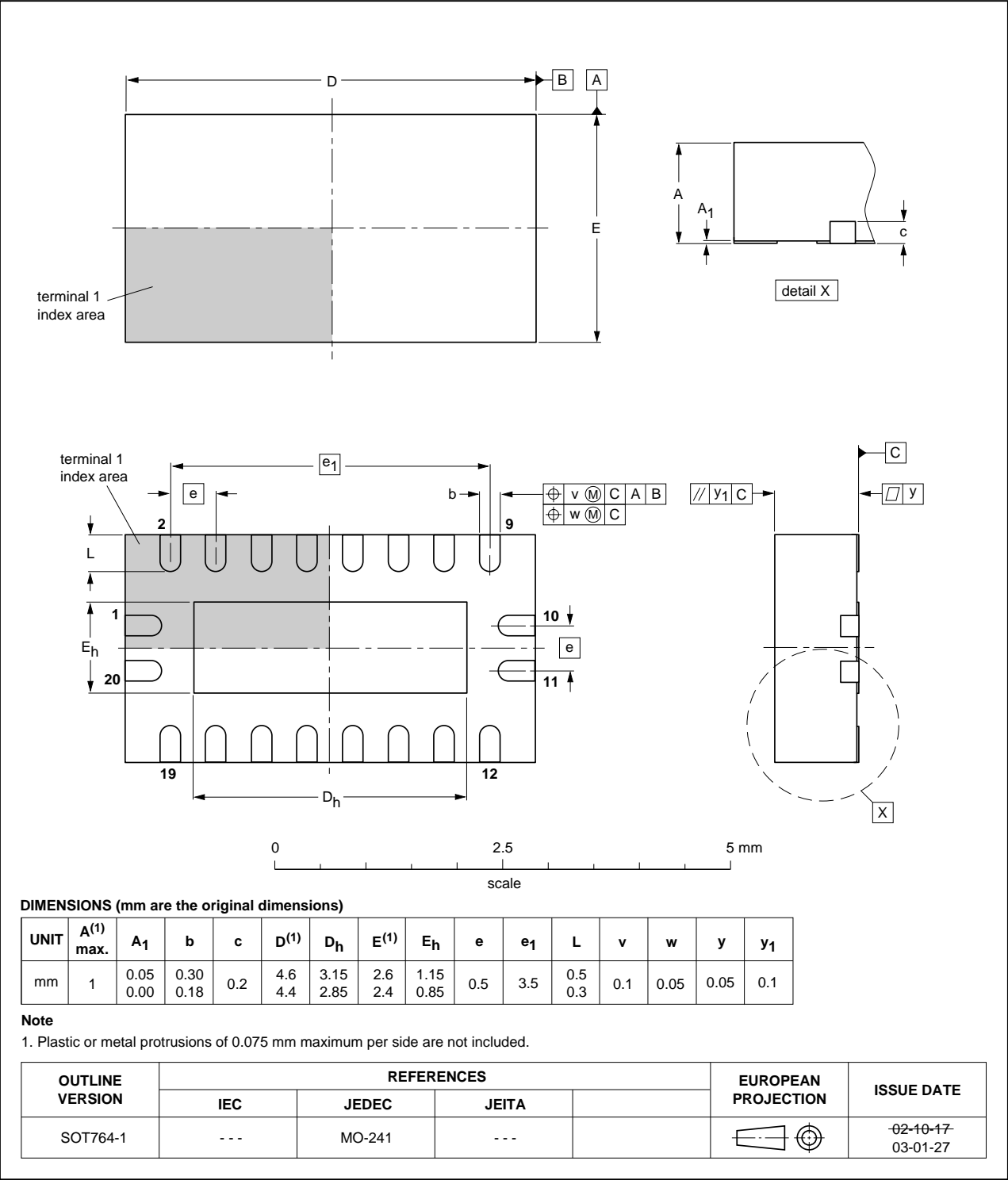


Fig 12. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC_LVCH244A_Q100 v.2	20130813	Product data sheet	-	74LVC_LVCH244A_Q100 v.1
Modifications:	• 74LVC244ADB-Q100 and 74LVCH244DB-Q100 added.			
74LVC_LVCH244A_Q100 v.1	20120823	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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